		Search Text	DB	Time stamp
Number	2	20/c gala and galder with (reference	USPAT;	2004/04/02
29	2	29/\$.ccls. and solder with (reference referring) same detect\$3 same (land pad)	EPO; JPO	13:52
30	12	and print\$3 near position and mounting solder\$3 with (reference referring) same	USPAT;	2004/04/02
		detect\$3 same (land pad) and print\$3 near position same detect\$3 and mounting	EPO; JPO	14:04
31	2	solder\$3 with paste with (reference referring) and detect\$3 same (land pad)	USPAT; EPO; JPO	2004/04/02 14:11
32	5	<pre>same print\$3 near position and mounting solder\$3 with paste with (reference</pre>	USPAT;	2004/04/02
		referring) and detect\$3 same position and mounting same (land pad) same printing	EPO; JPO	14:22
33	6	solder\$3 with paste with (reference referring) and detect\$3 same position and	USPAT; EPO; JPO	2004/04/02
		mounting with component and (land pad) same printing		
34	8	solder\$3 with paste with (reference referring) and detect\$3 same position and	USPAT; EPO; JPO	2004/04/02
35	11	mounting and (land pad) and printing solder\$3 with paste with (reference	USPAT;	2004/04/02
35	11	referring) and detect\$3 same position and	EPO; JPO	14:35
36	1	mounting and printing solder\$3 with paste with (reference	USPAT;	2004/04/02
	_	referring) and detect\$3 same position and self\$lalignment	EPO; JPO	14:35
37	2	solder\$3 with paste with (reference referring) and detect\$3 and position and	USPAT; EPO; JPO	2004/04/02 14:36
38	1	self\$lalignment solder\$3 with paste with (reference	USPAT;	2004/04/02
		referring mark marking) same detect\$3 and position and self\$lalignment	EPO; JPO	14:36
39	1	solder\$3 with paste with (reference referring mark marking) same detect\$3 and	USPAT; EPO; JPO	2004/04/02 14:37
		(mark\$3 position location) and self\$lalignment		
40	2	solder\$3 with paste with (reference referring mark marking) and detect\$3 and	USPAT; EPO; JPO	2004/04/02 14:47
		<pre>(mark\$3 position location) and self\$lalignment</pre>		
41	2	solder\$3 with paste with detect\$3 and (mark\$3 position location) and	USPAT; EPO; JPO	2004/04/02 14:49
		self\$1alignment		
42	23	solder\$3 with paste with detect\$3 and (mark\$3 position location) and printing	USPAT; EPO; JPO	2004/04/02 15:14
43	18	and mounting solder\$3 with paste with detect\$3 and	USPAT;	2004/04/02
	10	(decid\$3 set\$4 calculat\$3) and printing and mounting	EPO; JPO	18:09
59	1	382/\$.ccls. and solder\$3 with paste with detect\$3 and printing and mounting	USPAT; EPO; JPO	2004/04/02 18:10
60	1	73/\$.ccls. and solder\$3 with paste with detect\$3 and printing and mounting	USPAT; EPO; JPO	2004/04/02
61	4	l	USPAT; EPO; JPO	2004/04/02 18:11
-	4	mounting with component.ti. and nobuyasu.in.	USPAT; US-PGPUB;	2004/04/01 11:42
_	14		EPO; JPO USPAT;	2004/03/31
	14	paste and mounting with component and	EPO; JPO	18:26
-	3	refer\$4 with position mounting with component and detecting with printing with position and solder	USPAT; EPO; JPO	2004/04/01 15:00
		adj paste same (land pad) and (referring	EFO; UPO	15:00
_	5	reference) mounting with component and detecting	USPAT;	2004/04/01
	-	with printing with position and (controler controlling) and feed with	EPO; JPO	15:02
		forward and (referring reference)		

			VIO D 3 M .	2004/04/01
-	0	mounting with component and detecting	USPAT;	2004/04/01
1		with printing and position with solder	EPO; JPO	15:02
		and (controler controlling) and feed with		
		forward and (referring reference)	ļ	
-	0	mounting with component and detecting	USPAT;	2004/04/01
		with printing and position with solder\$3	EPO; JPO	15:03
		and (controler controlling) and feed with		
		forward and (referring reference)		
_	4	mounting with component and detecting	USPAT;	2004/04/01
		with printing and position with (land	EPO; JPO	15:04
		pad) and (controler controlling) and feed		
		with forward and (referring reference)		
_	0	mounting with component and detecting	USPAT;	2004/04/01
	•	with printing and position with (land	EPO; JPO	15:05
		pad) and control\$4 and feed with forward	210, 010	1 20.00
		and (referring reference) same solder\$4		
_	4	mounting with component and detecting	USPAT;	2004/04/01
	3	with printing and position with (land	EPO; JPO	15:07
		pad) and control\$4 and (referring	HEO, 010	13.07
		reference) same solder\$4		
	1	29/\$.ccls. and mounting with component	USPAT;	2004/04/01
_	1	and detecting same printing and position	EPO; JPO	15:10
		with (land pad) and control\$4 and	EPO, JPO	13.10
		(referring reference) same solder\$4		
	13386		USPAT;	2004/04/01
-	13306	29/\$.ccls. and mounting with component		15:11
		and detecting same printing same position	EPO; JPO	15:11
		and control\$4 and (referring reference)		
	o	same solder\$4 feed near2 forward	HCDAM.	2004/04/01
-	U	29/\$.ccls. and mounting with component	USPAT;	, ,
		and detecting same printing same position	EPO; JPO	15:12
		and control\$4 and (referring reference)	i	
		same solder\$4 and feed near2 forward		2024/04/03
-	0	mounting with component and detecting	USPAT;	2004/04/01
		same printing same position and control\$4	EPO; JPO	15:13
		and (referring reference) same solder\$4		
	_	and feed\$3 near2 forward	TYCDAE.	2004/04/01
-	0	mounting with component and detecting	USPAT;	2004/04/01
		same printing same (mark position) and	EPO; JPO	15:13
		control\$4 and (referring reference) same		
	_	solder\$4 and feed\$3 near2 forward	***************************************	2004/04/03
-	0	mounting with component and detecting	USPAT;	2004/04/01
		same printing and control\$4 and	EPO; JPO	15:14
1		(referring reference) same solder\$4 same		1
	_	(mark position) and feed\$3 near2 forward		2004/04/03
-	0	mounting with component and detecting	USPAT;	2004/04/01
		same printing and control\$4 and	EPO; JPO	15:14
		(referring reference) same solder\$4 and		
	_	feed\$3 near2 forward		
-	8	mounting with component and detecting	USPAT;	2004/04/01
		same printing and control\$4 and	EPO; JPO	15:15
		(referring reference) same solder\$4 same]	1
		(mark position)	1	<u> </u>